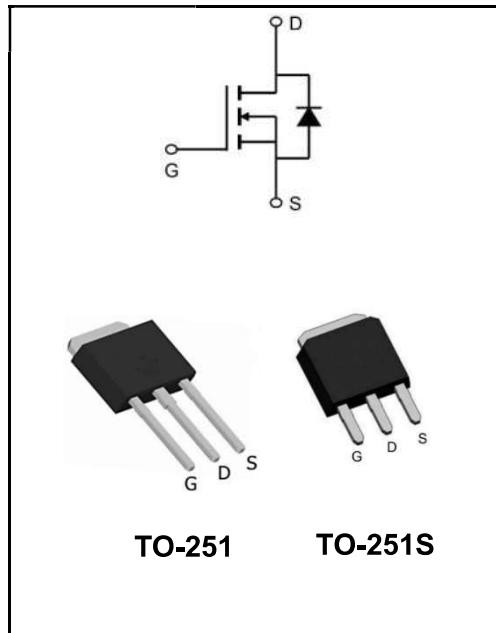


**60V N-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	30A
$V_{DSS}$	60V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 36mΩ (Type: 28 mΩ)


**Application**

- ◆ LED lamp
- ◆ Load switch
- ◆ Uninterruptible power supply

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW30N06AMJ	TO-251	YFW 30N06AMJ XXXXX	4000PCS/Tape
YFW30N06AMJ	TO-251S	YFW 30N06AMJ XXXXX	4000PCS/Tape

**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	60	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=25^\circ\text{C}$	$I_D$	30	A
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=100^\circ\text{C}$	$I_D$	13	A
Pulsed Drain Current	$I_{DM}$	74	A
Avalanche Current	$I_{AS}$	13	A
Single Pulse Avalanche Energy	$E_{AS}$	22	mJ
Power Dissipation @ $T_c=25^\circ\text{C}$	$P_D$	31.3	W
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +175	°C
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	62	°C/W
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	4	°C/W

**Maximum Ratings at Tc=25°C unless otherwise specified**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	BV <sub>DSS</sub>	60	65	-	V
BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	ΔBV <sub>DSS/ΔTJ</sub>	-	0.044	-	V/°C
Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =15A	R <sub>DS(ON)</sub>	-	28	36	mΩ
	V <sub>GS</sub> =4.5V, I <sub>D</sub> =7A		-	38	45	
Gate -Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	V <sub>GS(th)</sub>	1.2	1.6	2.5	V
V <sub>GS(th)</sub> Temperature Coefficient		ΔV <sub>GS(th)</sub>	-	-4.8	-	mV/°C
Drain -Source Leakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	I <sub>DSS</sub>	-	-	1	μA
	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C		-	-	5	
Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	I <sub>GSS</sub>	-	-	±100	nA
Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =15A	g <sub>FS</sub>	-	25.3	-	S
Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	R <sub>G</sub>	-	2.5	-	Ω
Total Gate Charge(10V)	V <sub>DS</sub> =48V V <sub>GS</sub> =10V I <sub>D</sub> =15A	Q <sub>g</sub>	-	19	-	nC
Gate-Source Charge		Q <sub>gs</sub>	-	2.5	-	
Gate-Drain Charge		Q <sub>gd</sub>	-	5	-	
Turn-on delay time	V <sub>DD</sub> =30V V <sub>GS</sub> =10V R <sub>G</sub> =3.3Ω I <sub>D</sub> =15A	t <sub>d(on)</sub>	-	2.8	-	ns
Rise Time		T <sub>r</sub>	-	16.6	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	21.2	-	
Fall Time		t <sub>f</sub>	-	5.6	-	
Input Capacitance	V <sub>DS</sub> =15V V <sub>GS</sub> =0V f=1.0MHz	C <sub>iss</sub>	-	1027	-	pF
Output Capacitance		C <sub>oss</sub>	-	65	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	46	-	
Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	I <sub>s</sub>	-	-	20	A
Pulsed Source Current <sup>2,6</sup>		I <sub>SM</sub>	-	-	40	A
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>s</sub> =1A , T <sub>J</sub> =25°C	V <sub>SD</sub>	-	-	1.2	V
Reverse Recovery Time	I <sub>F</sub> =15A , dI/dt=100A/μs , T <sub>J</sub> =25°C	t <sub>rr</sub>	-	12.2	-	nS
Reverse Recovery Charge		Q <sub>rr</sub>	-	7.3	-	nC

Note :

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The test cond $\leq$  300us duty cycle  $\leq$  2%, duty cycle ition is T<sub>J</sub> =25°C, VDD =48V, VG =10V, RG =25Ω, L=0.1mH, IAS =13A
- 4、The power dissipation is limited by 175°C junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

Typical Characteristics

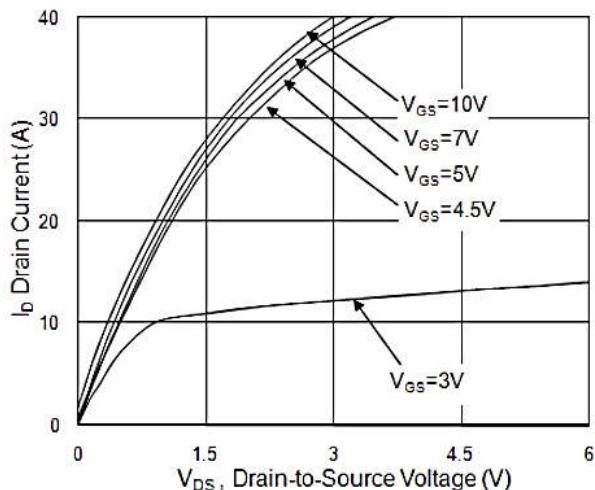


Fig.1 Typical Output Characteristics

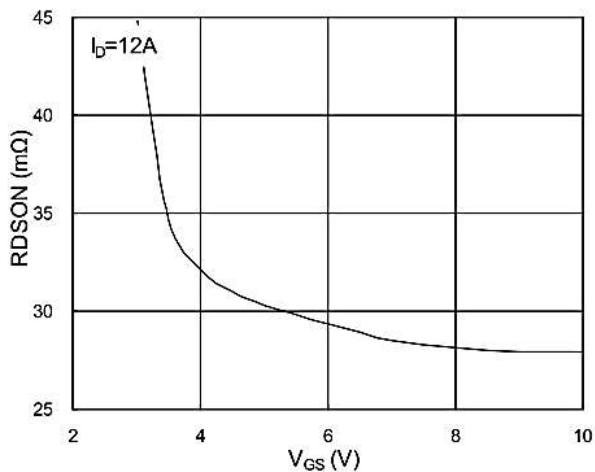


Fig.2 On-Resistance vs. Gate-Source

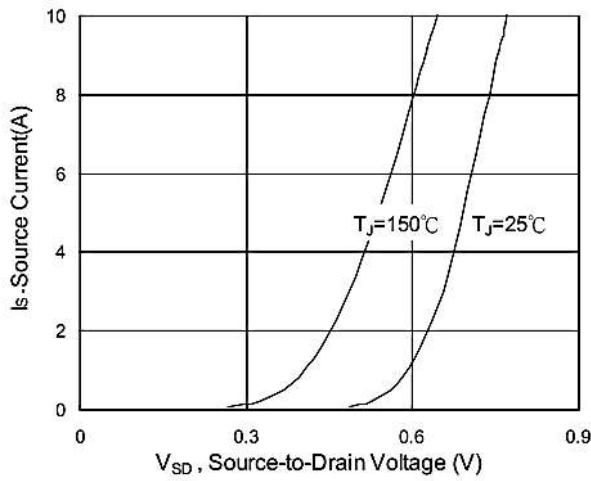


Fig.3 Forward Characteristics Of Reverse

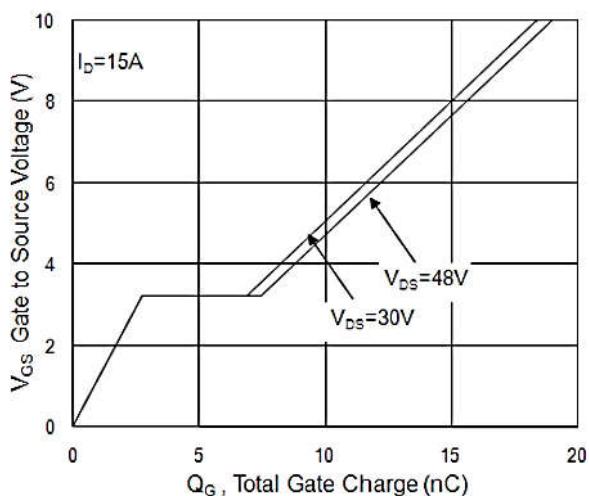


Fig.4 Gate-Charge Characteristics

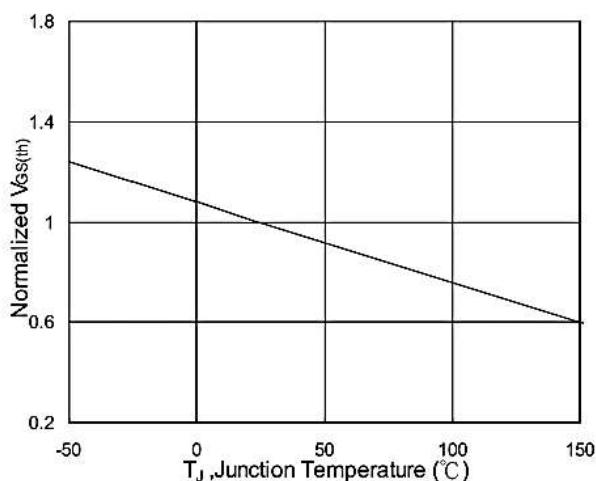


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

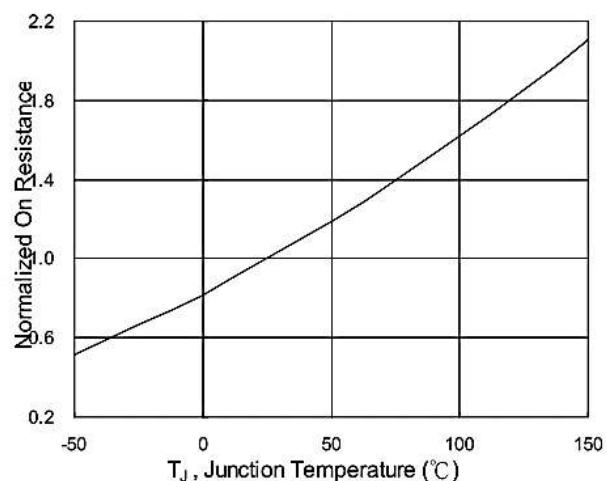
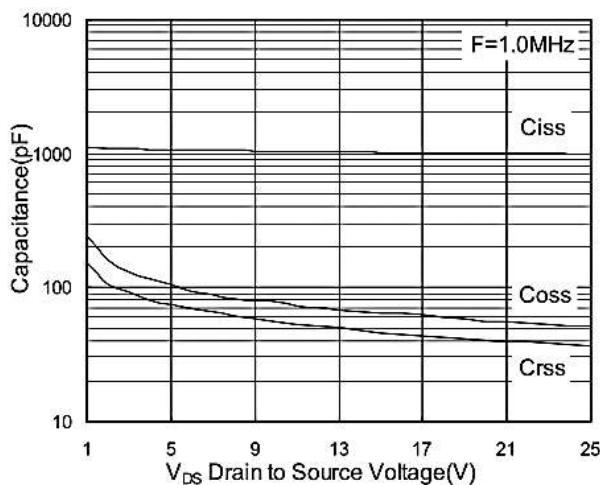
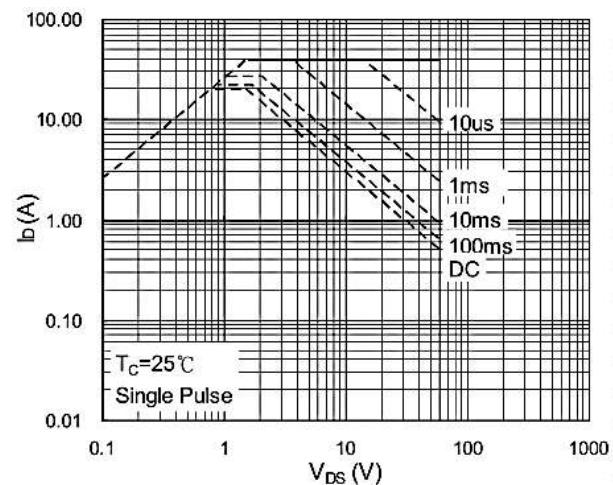
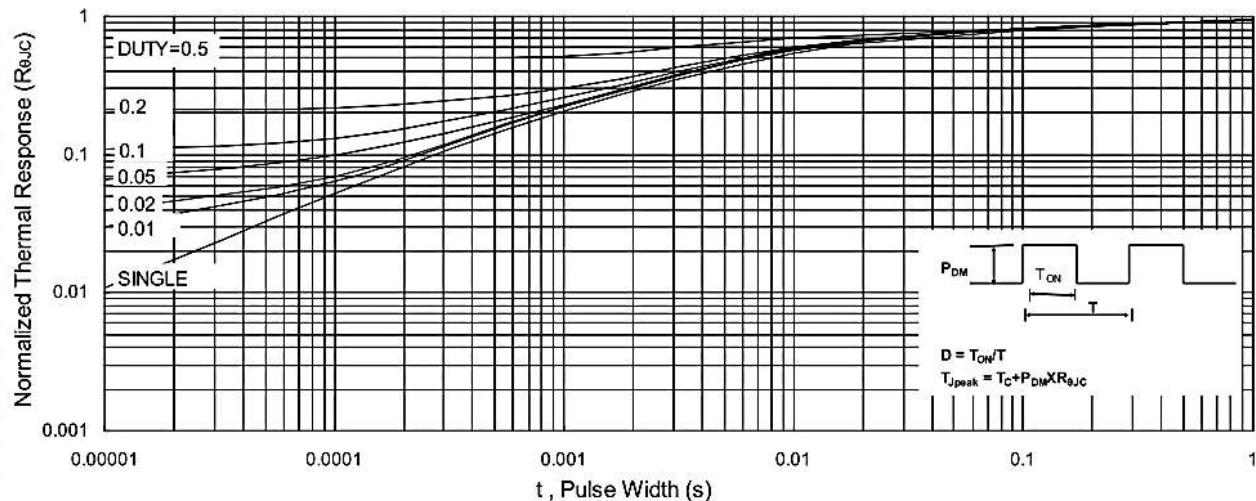
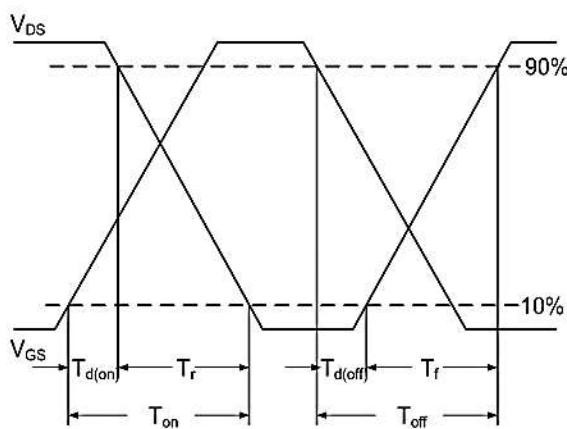
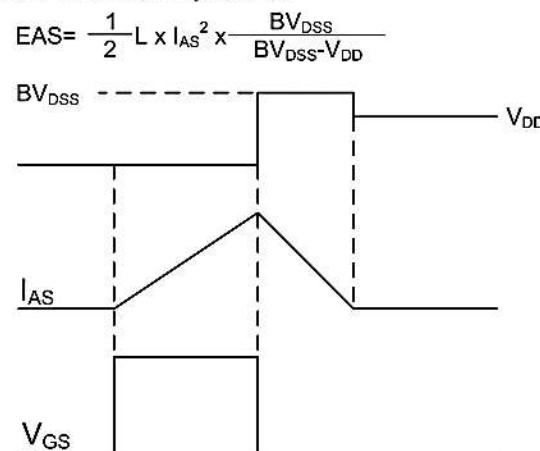
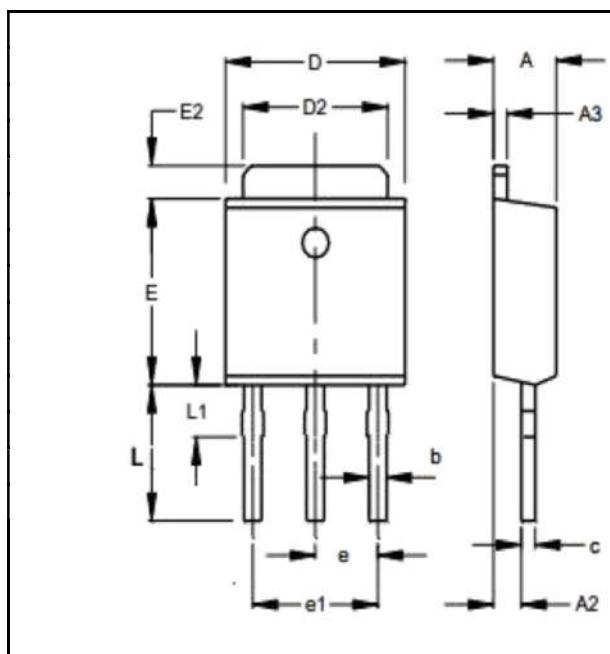


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>

**Ratings and Characteristic Curves**

**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**

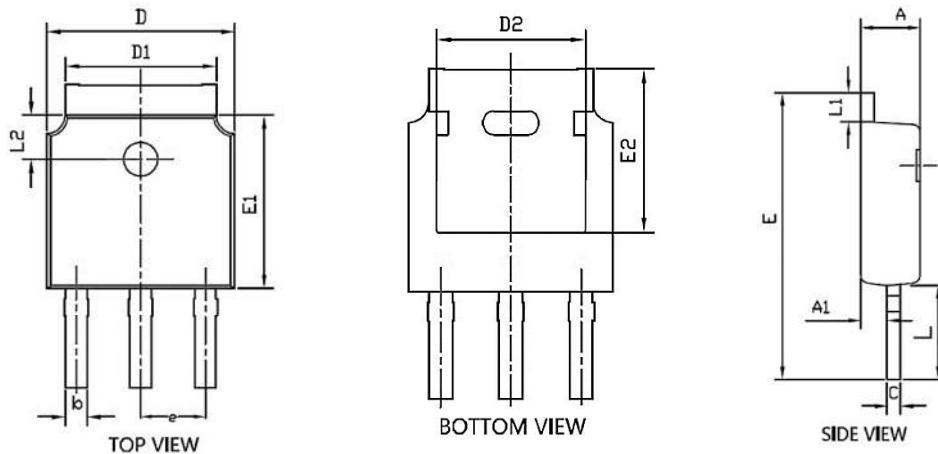
**Package Outline Dimensions Millimeters**

**TO-251**



Dim.	Min.	Max.
A	2.2	2.4
A2	0.95	1.15
A3	0.45	0.65
b	0.65	0.85
c	0.45	0.55
D	6.45	6.75
D2	5.2	5.4
E	5.8	6
E2	0.95	1.25
e	Typ 2.3	
e1	Typ 4.6	
L	4	4.2
L1	1.2	1.5

All Dimensions in millimeter

**Package Outline Dimensions Millimeters**
**TO-251S**


Symbol	Common		
	mm		
	Mim	Nom	Max
A	2.2	2.3	2.4
A1	0.9	1.0	1.1
b	0.66	0.76	0.86
C	0.46	0.52	0.58
D	6.50	6.6	6.7
D1	5.15	5.3	5.45
D2	4.6	4.8	4.95
E	10.4	----	11.5
E1	6.0	6.1	6.2
E2	5.400REF		
e	2.286BSC		
L	3.5	4.0	4.3
L1	0.9	---	1.27
L2	1.4	---	1.9